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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

|                            |   |
|----------------------------|---|
| Product Status             | Obsolete  |
| Core Processor             | S08   |
| Core Size                  | 8-Bit   |
| Speed                      | 40MHz   |
| Connectivity               | CANbus, I <sup>2</sup> C, LINbus, SCI, SPI  |
| Peripherals                | LVD, POR, PWM, WDT  |
| Number of I/O              | 25  |
| Program Memory Size        | 32KB (32K x 8)  |
| Program Memory Type        | FLASH   |
| EEPROM Size                | -   |
| RAM Size                   | 2K x 8  |
| Voltage - Supply (Vcc/Vdd) | 2.7V ~ 5.5V   |
| Data Converters            | A/D 10x12b  |
| Oscillator Type            | External  |
| Operating Temperature      | -40°C ~ 125°C (TA)  |
| Mounting Type              | Surface Mount   |
| Package / Case             | 32-LQFP   |
| Supplier Device Package    | 32-LQFP (7x7)   |
| Purchase URL               | <a href="https://www.e-xfl.com/pro/item?MUrl=&amp;PartUrl=mc9s08dv32amlcr">https://www.e-xfl.com/pro/item?MUrl=&amp;PartUrl=mc9s08dv32amlcr</a> |

## 2.2.1 Power

$V_{DD}$  and  $V_{SS}$  are the primary power supply pins for the MCU. This voltage source supplies power to all I/O buffer circuitry and to an internal voltage regulator. The internal voltage regulator provides regulated lower-voltage source to the CPU and other internal circuitry of the MCU.

Typically, application systems have two separate capacitors across the power pins. In this case, there should be a bulk electrolytic capacitor, such as a 10- $\mu$ F tantalum capacitor, to provide bulk charge storage for the overall system and a 0.1- $\mu$ F ceramic bypass capacitor located as near to the MCU power pins as practical to suppress high-frequency noise. The MC9S08DV60 Series has two  $V_{DD}$  pins except on the 32-pin package. Each pin must have a bypass capacitor for best noise suppression.

$V_{DDA}$  and  $V_{SSA}$  are the analog power supply pins for the MCU. This voltage source supplies power to the ADC module. A 0.1- $\mu$ F ceramic bypass capacitor should be located as near to the MCU power pins as practical to suppress high-frequency noise.

## 2.2.2 Oscillator

Immediately after reset, the MCU uses an internally generated clock provided by the multi-purpose clock generator (MCG) module. For more information on the MCG, see [Chapter 8, “Multi-Purpose Clock Generator \(S08MCGV1\).”](#)

The oscillator (XOSC) in this MCU is a Pierce oscillator that can accommodate a crystal or ceramic resonator. Rather than a crystal or ceramic resonator, an external oscillator can be connected to the EXTAL input pin.

Refer to [Figure 2-4](#) for the following discussion.  $R_S$  (when used) and  $R_F$  should be low-inductance resistors such as carbon composition resistors. Wire-wound resistors and some metal film resistors have too much inductance. C1 and C2 normally should be high-quality ceramic capacitors that are specifically designed for high-frequency applications.

$R_F$  is used to provide a bias path to keep the EXTAL input in its linear range during crystal startup; its value is not generally critical. Typical systems use 1 M $\Omega$  to 10 M $\Omega$ . Higher values are sensitive to humidity, and lower values reduce gain and (in extreme cases) could prevent startup.

C1 and C2 are typically in the 5-pF to 25-pF range and are chosen to match the requirements of a specific crystal or resonator. Be sure to take into account printed circuit board (PCB) capacitance and MCU pin capacitance when selecting C1 and C2. The crystal manufacturer typically specifies a load capacitance which is the series combination of C1 and C2 (which are usually the same size). As a first-order approximation, use 10 pF as an estimate of combined pin and PCB capacitance for each oscillator pin (EXTAL and XTAL).

## 2.2.3 $\overline{\text{RESET}}$

$\overline{\text{RESET}}$  is a dedicated pin with a pull-up device built in. It has input hysteresis, a high current output driver, and no output slew rate control. Internal power-on reset and low-voltage reset circuitry typically make external reset circuitry unnecessary. This pin is normally connected to the standard 6-pin background debug connector so a development system can directly reset the MCU system. If desired, a manual external reset can be added by supplying a simple switch to ground (pull reset pin low to force a reset).

**Table 4-1. Reset and Interrupt Vectors**

| Address<br>(High/Low) | Vector                 | Vector Name |
|-----------------------|------------------------|-------------|
| 0xFFCE:0xFFCF         | IIC                    | Viic        |
| 0xFFD0:0xFFD1         | ADC Conversion         | Vadc        |
| 0xFFD2:0xFFD3         | Port A, Port B, Port D | Vport       |
| 0xFFD4:0xFFD5         | SCI2 Transmit          | Vsci2tx     |
| 0xFFD6:0xFFD7         | SCI2 Receive           | Vsci2rx     |
| 0xFFD8:0xFFD9         | SCI2 Error             | Vsci2err    |
| 0xFFDA:0xFFDB         | SCI1 Transmit          | Vsci1tx     |
| 0xFFDC:0xFFDD         | SCI1 Receive           | Vsci1rx     |
| 0xFFDE:0xFFDF         | SCI1 Error             | Vsci1err    |
| 0xFFE0:0xFFE1         | SPI                    | Vspi        |
| 0xFFE2:0xFFE3         | TPM2 Overflow          | Vtpm2ovf    |
| 0xFFE4:0xFFE5         | TPM2 Channel 1         | Vtpm2ch1    |
| 0xFFE6:0xFFE7         | TPM2 Channel 0         | Vtpm2ch0    |
| 0xFFE8:0xFFE9         | TPM1 Overflow          | Vtpm1ovf    |
| 0xFFEA:0xFFEB         | TPM1 Channel 5         | Vtpm1ch5    |
| 0xFFEC:0xFFED         | TPM1 Channel 4         | Vtpm1ch4    |
| 0xFFEE:0xFFEF         | TPM1 Channel 3         | Vtpm1ch3    |
| 0xFFF0:0xFFF1         | TPM1 Channel 2         | Vtpm1ch2    |
| 0xFFF2:0xFFF3         | TPM1 Channel 1         | Vtpm1ch1    |
| 0xFFF4:0xFFF5         | TPM1 Channel 0         | Vtpm1ch0    |
| 0xFFF6:0xFFF7         | MCG Loss of lock       | Vlol        |
| 0xFFF8:0xFFF9         | Low-Voltage Detect     | Vlvd        |
| 0xFFFA:0xFFFB         | IRQ                    | Virq        |
| 0xFFFC:0xFFFD         | SWI                    | Vswi        |
| 0xFFFE:0xFFFF         | Reset                  | Vreset      |

## 4.5.10 Flash Registers and Control Bits

The Flash module has seven 8-bit registers in the high-page register space and three locations in the nonvolatile register space in Flash memory. Two of those locations are copied into two corresponding high-page control registers at reset. There is also an 8-byte comparison key in Flash memory. Refer to [Table 4-3](#) and [Table 4-5](#) for the absolute address assignments for all Flash registers. This section refers to registers and control bits only by their names. A Freescale Semiconductor-provided equate or header file normally is used to translate these names into the appropriate absolute addresses.

### 4.5.10.1 Flash Clock Divider Register (FCDIV)

Bit 7 of this register is a read-only flag. Bits 6:0 may be read at any time but can be written only one time. Before any erase or programming operations are possible, write to this register to set the frequency of the clock for the nonvolatile memory system within acceptable limits.

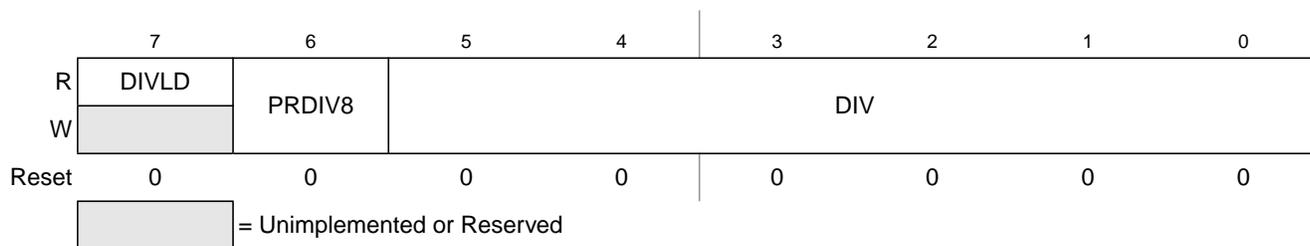


Figure 4-5. Flash Clock Divider Register (FCDIV)

Table 4-7. FCDIV Register Field Descriptions

| Field       | Description  |
|-------------|--|
| 7<br>DIVLD  | <b>Divisor Loaded Status Flag</b> — When set, this read-only status flag indicates that the FCDIV register has been written since reset. Reset clears this bit and the first write to this register causes this bit to become set regardless of the data written.<br>0 FCDIV has not been written since reset; erase and program operations disabled for Flash.<br>1 FCDIV has been written since reset; erase and program operations enabled for Flash.   |
| 6<br>PRDIV8 | <b>Prescale (Divide) Flash Clock by 8</b> (This bit is write once.)<br>0 Clock input to the Flash clock divider is the bus rate clock.<br>1 Clock input to the Flash clock divider is the bus rate clock divided by 8.   |
| 5:0<br>DIV  | <b>Divisor for Flash Clock Divider</b> — These bits are write once. The Flash clock divider divides the bus rate clock (or the bus rate clock divided by 8 if PRDIV8 = 1) by the value in the 6-bit DIV field plus one. The resulting frequency of the internal Flash clock must fall within the range of 200 kHz to 150 kHz for proper Flash operations. Program/Erase timing pulses are one cycle of this internal Flash clock which corresponds to a range of 5 μs to 6.7 μs. The automated programming logic uses an integer number of these pulses to complete an erase or program operation. See <a href="#">Equation 4-1</a> and <a href="#">Equation 4-2</a> . |

$$\text{if PRDIV8} = 0 \text{ — } f_{\text{FCLK}} = f_{\text{Bus}} \div (\text{DIV} + 1) \quad \text{Eqn. 4-1}$$

$$\text{if PRDIV8} = 1 \text{ — } f_{\text{FCLK}} = f_{\text{Bus}} \div (8 \times (\text{DIV} + 1)) \quad \text{Eqn. 4-2}$$

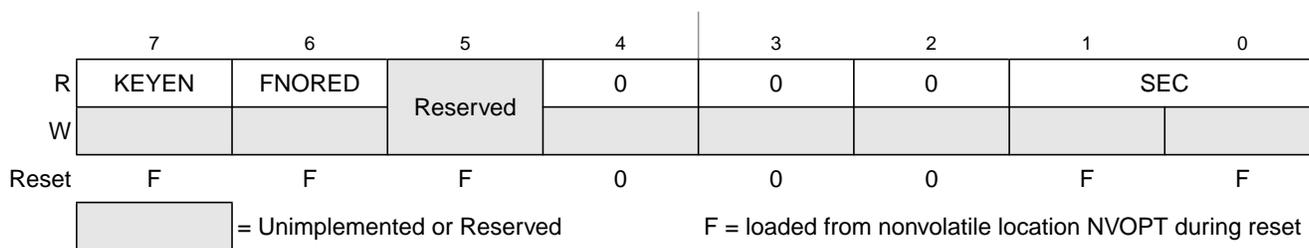
[Table 4-8](#) shows the appropriate values for PRDIV8 and DIV for selected bus frequencies.

**Table 4-8. Flash Clock Divider Settings**

| f <sub>Bus</sub> | PRDIV8 (Binary) | DIV (Decimal) | f <sub>FCLK</sub> | Program/Erase Timing Pulse (5 μs Min, 6.7 μs Max) |
|------------------|-----------------|---------------|-------------------|---|
| 20 MHz           | 1               | 12            | 192.3 kHz         | 5.2 μs  |
| 10 MHz           | 0               | 49            | 200 kHz           | 5 μs  |
| 8 MHz            | 0               | 39            | 200 kHz           | 5 μs  |
| 4 MHz            | 0               | 19            | 200 kHz           | 5 μs  |
| 2 MHz            | 0               | 9             | 200 kHz           | 5 μs  |
| 1 MHz            | 0               | 4             | 200 kHz           | 5 μs  |
| 200 kHz          | 0               | 0             | 200 kHz           | 5 μs  |
| 150 kHz          | 0               | 0             | 150 kHz           | 6.7 μs  |

### 4.5.10.2 Flash Options Register (FOPT and NVOPT)

During reset, the contents of the nonvolatile location NVOPT are copied from Flash into FOPT. To change the value in this register, erase and reprogram the NVOPT location in Flash memory as usual and then issue a new MCU reset.



**Figure 4-6. Flash Options Register (FOPT)**

**Table 4-9. FOPT Register Field Descriptions**

| Field       | Description  |
|-------------|--|
| 7<br>KEYEN  | <b>Backdoor Key Mechanism Enable</b> — When this bit is 0, the backdoor key mechanism cannot be used to disengage security. The backdoor key mechanism is accessible only from user (secured) firmware. BDM commands cannot be used to write key comparison values that would unlock the backdoor key. For more detailed information about the backdoor key mechanism, refer to <a href="#">Section 4.5.9, “Security.”</a><br>0 No backdoor key access allowed.<br>1 If user firmware writes an 8-byte value that matches the nonvolatile backdoor key (NVBACKKEY through NVBACKKEY+7 in that order), security is temporarily disengaged until the next MCU reset. |
| 6<br>FNORED | <b>Vector Redirection Disable</b> — When this bit is 1, then vector redirection is disabled.<br>0 Vector redirection enabled.<br>1 Vector redirection disabled.  |
| 1:0<br>SEC  | <b>Security State Code</b> — This 2-bit field determines the security state of the MCU as shown in <a href="#">Table 4-10</a> . When the MCU is secure, the contents of RAM and Flash memory cannot be accessed by instructions from any unsecured source including the background debug interface. SEC changes to 1:0 after successful backdoor key entry or a successful blank check of Flash. For more detailed information about security, refer to <a href="#">Section 4.5.9, “Security.”</a>   |

## 5.5.1 Interrupt Stack Frame

Figure 5-1 shows the contents and organization of a stack frame. Before the interrupt, the stack pointer (SP) points at the next available byte location on the stack. The current values of CPU registers are stored on the stack starting with the low-order byte of the program counter (PCL) and ending with the CCR. After stacking, the SP points at the next available location on the stack which is the address that is one less than the address where the CCR was saved. The PC value that is stacked is the address of the instruction in the main program that would have executed next if the interrupt had not occurred.

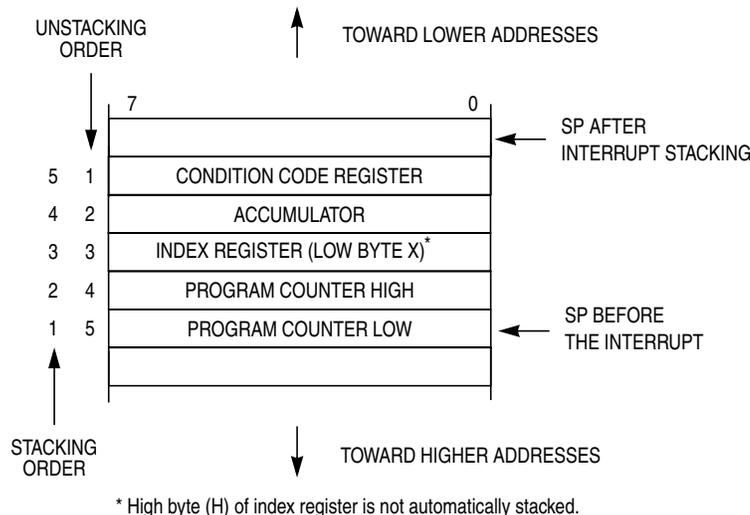


Figure 5-1. Interrupt Stack Frame

When an RTI instruction is executed, these values are recovered from the stack in reverse order. As part of the RTI sequence, the CPU fills the instruction pipeline by reading three bytes of program information, starting from the PC address recovered from the stack.

The status flag corresponding to the interrupt source must be acknowledged (cleared) before returning from the ISR. Typically, the flag is cleared at the beginning of the ISR so that if another interrupt is generated by this same source, it will be registered so it can be serviced after completion of the current ISR.

## 5.5.2 External Interrupt Request (IRQ) Pin

External interrupts are managed by the IRQ status and control register, IRQSC. When the IRQ function is enabled, synchronous logic monitors the pin for edge-only or edge-and-level events. When the MCU is in stop mode and system clocks are shut down, a separate asynchronous path is used so the IRQ (if enabled) can wake the MCU.

### 5.5.2.1 Pin Configuration Options

The IRQ pin enable (IRQPE) control bit in IRQSC must be 1 in order for the IRQ pin to act as the interrupt request (IRQ) input. As an IRQ input, the user can choose the polarity of edges or levels detected (IRQEDG), whether the pin detects edges-only or edges and levels (IRQMOD), and whether an event causes an interrupt or only sets the IRQF flag which can be polled by software.

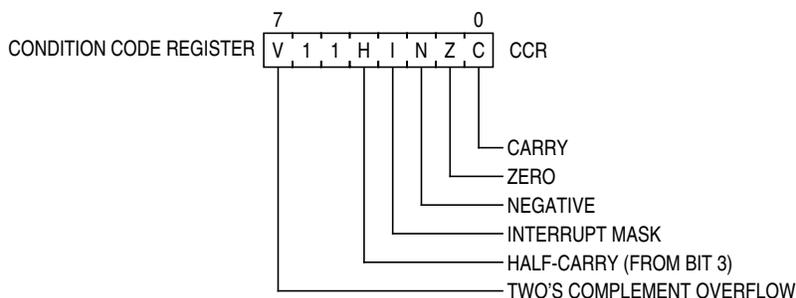


Figure 7-2. Condition Code Register

Table 7-1. CCR Register Field Descriptions

| Field  | Description   |
|--------|---|
| 7<br>V | <b>Two's Complement Overflow Flag</b> — The CPU sets the overflow flag when a two's complement overflow occurs. The signed branch instructions BGT, BGE, BLE, and BLT use the overflow flag.<br>0 No overflow<br>1 Overflow   |
| 4<br>H | <b>Half-Carry Flag</b> — The CPU sets the half-carry flag when a carry occurs between accumulator bits 3 and 4 during an add-without-carry (ADD) or add-with-carry (ADC) operation. The half-carry flag is required for binary-coded decimal (BCD) arithmetic operations. The DAA instruction uses the states of the H and C condition code bits to automatically add a correction value to the result from a previous ADD or ADC on BCD operands to correct the result to a valid BCD value.<br>0 No carry between bits 3 and 4<br>1 Carry between bits 3 and 4  |
| 3<br>I | <b>Interrupt Mask Bit</b> — When the interrupt mask is set, all maskable CPU interrupts are disabled. CPU interrupts are enabled when the interrupt mask is cleared. When a CPU interrupt occurs, the interrupt mask is set automatically after the CPU registers are saved on the stack, but before the first instruction of the interrupt service routine is executed.<br>Interrupts are not recognized at the instruction boundary after any instruction that clears I (CLI or TAP). This ensures that the next instruction after a CLI or TAP will always be executed without the possibility of an intervening interrupt, provided I was set.<br>0 Interrupts enabled<br>1 Interrupts disabled |
| 2<br>N | <b>Negative Flag</b> — The CPU sets the negative flag when an arithmetic operation, logic operation, or data manipulation produces a negative result, setting bit 7 of the result. Simply loading or storing an 8-bit or 16-bit value causes N to be set if the most significant bit of the loaded or stored value was 1.<br>0 Non-negative result<br>1 Negative result   |
| 1<br>Z | <b>Zero Flag</b> — The CPU sets the zero flag when an arithmetic operation, logic operation, or data manipulation produces a result of 0x00 or 0x0000. Simply loading or storing an 8-bit or 16-bit value causes Z to be set if the loaded or stored value was all 0s.<br>0 Non-zero result<br>1 Zero result  |
| 0<br>C | <b>Carry/Borrow Flag</b> — The CPU sets the carry/borrow flag when an addition operation produces a carry out of bit 7 of the accumulator or when a subtraction operation requires a borrow. Some instructions — such as bit test and branch, shift, and rotate — also clear or set the carry/borrow flag.<br>0 No carry out of bit 7<br>1 Carry out of bit 7   |

## 7.3 Addressing Modes

Addressing modes define the way the CPU accesses operands and data. In the HCS08, all memory, status and control registers, and input/output (I/O) ports share a single 64-Kbyte linear address space so a 16-bit binary address can uniquely identify any memory location. This arrangement means that the same instructions that access variables in RAM can also be used to access I/O and control registers or nonvolatile program space.

Some instructions use more than one addressing mode. For instance, move instructions use one addressing mode to specify the source operand and a second addressing mode to specify the destination address. Instructions such as BRCLR, BRSET, CBEQ, and DBNZ use one addressing mode to specify the location of an operand for a test and then use relative addressing mode to specify the branch destination address when the tested condition is true. For BRCLR, BRSET, CBEQ, and DBNZ, the addressing mode listed in the instruction set tables is the addressing mode needed to access the operand to be tested, and relative addressing mode is implied for the branch destination.

### 7.3.1 Inherent Addressing Mode (INH)

In this addressing mode, operands needed to complete the instruction (if any) are located within CPU registers so the CPU does not need to access memory to get any operands.

### 7.3.2 Relative Addressing Mode (REL)

Relative addressing mode is used to specify the destination location for branch instructions. A signed 8-bit offset value is located in the memory location immediately following the opcode. During execution, if the branch condition is true, the signed offset is sign-extended to a 16-bit value and is added to the current contents of the program counter, which causes program execution to continue at the branch destination address.

### 7.3.3 Immediate Addressing Mode (IMM)

In immediate addressing mode, the operand needed to complete the instruction is included in the object code immediately following the instruction opcode in memory. In the case of a 16-bit immediate operand, the high-order byte is located in the next memory location after the opcode, and the low-order byte is located in the next memory location after that.

### 7.3.4 Direct Addressing Mode (DIR)

In direct addressing mode, the instruction includes the low-order eight bits of an address in the direct page (0x0000–0x00FF). During execution a 16-bit address is formed by concatenating an implied 0x00 for the high-order half of the address and the direct address from the instruction to get the 16-bit address where the desired operand is located. This is faster and more memory efficient than specifying a complete 16-bit address for the operand.

interrupt service routine, this would allow nesting of interrupts (which is not recommended because it leads to programs that are difficult to debug and maintain).

For compatibility with the earlier M68HC05 MCUs, the high-order half of the H:X index register pair (H) is not saved on the stack as part of the interrupt sequence. The user must use a PSHH instruction at the beginning of the service routine to save H and then use a PULH instruction just before the RTI that ends the interrupt service routine. It is not necessary to save H if you are certain that the interrupt service routine does not use any instructions or auto-increment addressing modes that might change the value of H.

The software interrupt (SWI) instruction is like a hardware interrupt except that it is not masked by the global I bit in the CCR and it is associated with an instruction opcode within the program so it is not asynchronous to program execution.

### 7.4.3 Wait Mode Operation

The WAIT instruction enables interrupts by clearing the I bit in the CCR. It then halts the clocks to the CPU to reduce overall power consumption while the CPU is waiting for the interrupt or reset event that will wake the CPU from wait mode. When an interrupt or reset event occurs, the CPU clocks will resume and the interrupt or reset event will be processed normally.

If a serial BACKGROUND command is issued to the MCU through the background debug interface while the CPU is in wait mode, CPU clocks will resume and the CPU will enter active background mode where other serial background commands can be processed. This ensures that a host development system can still gain access to a target MCU even if it is in wait mode.

### 7.4.4 Stop Mode Operation

Usually, all system clocks, including the crystal oscillator (when used), are halted during stop mode to minimize power consumption. In such systems, external circuitry is needed to control the time spent in stop mode and to issue a signal to wake up the target MCU when it is time to resume processing. Unlike the earlier M68HC05 and M68HC08 MCUs, the HCS08 can be configured to keep a minimum set of clocks running in stop mode. This optionally allows an internal periodic signal to wake the target MCU from stop mode.

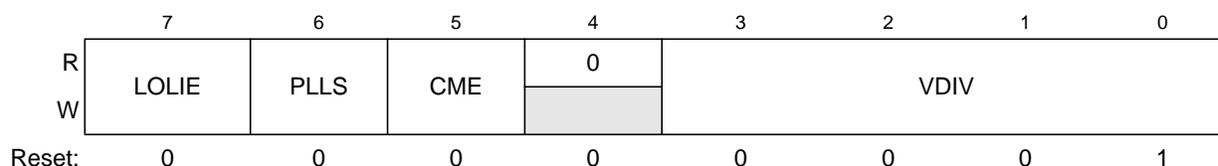
When a host debug system is connected to the background debug pin (BKGD) and the ENBDM control bit has been set by a serial command through the background interface (or because the MCU was reset into active background mode), the oscillator is forced to remain active when the MCU enters stop mode. In this case, if a serial BACKGROUND command is issued to the MCU through the background debug interface while the CPU is in stop mode, CPU clocks will resume and the CPU will enter active background mode where other serial background commands can be processed. This ensures that a host development system can still gain access to a target MCU even if it is in stop mode.

Recovery from stop mode depends on the particular HCS08 and whether the oscillator was stopped in stop mode. Refer to the [Modes of Operation](#) chapter for more details.

**Table 8-4. MCG Status and Control Register Field Descriptions (continued)**

| Field        | Description  |
|--------------|--|
| 1<br>OSCINIT | <b>OSC Initialization</b> — If the external reference clock is selected by ERCLKEN or by the MCG being in FEE, FBE, PEE, PBE, or BLPE mode, and if EREFS is set, then this bit is set after the initialization cycles of the external oscillator clock have completed. This bit is only cleared when either EREFS is cleared or when the MCG is in either FEI, FBI, or BLPI mode and ERCLKEN is cleared.         |
| 0<br>FTRIM   | <b>MCG Fine Trim</b> — Controls the smallest adjustment of the internal reference clock frequency. Setting FTRIM will increase the period and clearing FTRIM will decrease the period by the smallest amount possible.<br><br>If an FTRIM value stored in nonvolatile memory is to be used, it's the user's responsibility to copy that value from the nonvolatile memory location to this register's FTRIM bit. |

### 8.3.5 MCG Control Register 3 (MCGC3)



**Figure 8-7. MCG PLL Register (MCGPLL)**

**Table 8-5. MCG PLL Register Field Descriptions**

| Field      | Description  |
|------------|--|
| 7<br>LOLIE | <b>Loss of Lock Interrupt Enable</b> — Determines if an interrupt request is made following a loss of lock indication. The LOLIE bit only has an effect when LOLS is set.<br>0 No request on loss of lock.<br>1 Generate an interrupt request on loss of lock. |
| 6<br>PLLS  | <b>PLL Select</b> — Controls whether the PLL or FLL is selected. If the PLLS bit is clear, the PLL is disabled in all modes. If the PLLS is set, the FLL is disabled in all modes.<br>1 PLL is selected<br>0 FLL is selected                                   |

## 9.3 Memory Map/Register Definition

The ACMP includes one register:

- An 8-bit status and control register

Refer to the direct-page register summary in the memory section of this document for the absolute address assignments for the ACMP register. This section refers to register and control bits only by their names and relative address offsets.

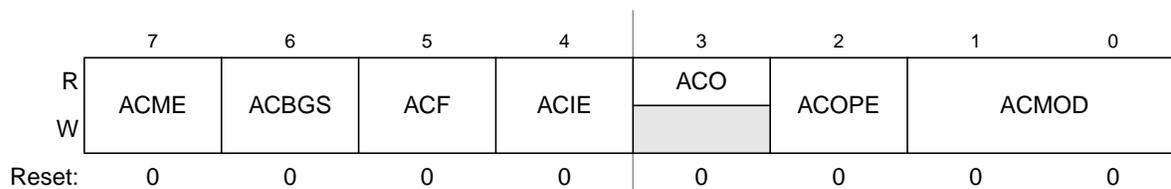
Some MCUs may have more than one ACMP, so register names include placeholder characters (x) to identify which ACMP is being referenced.

**Table 9-2. ACMP Register Summary**

| Name    |   | 7    | 6     | 5   | 4    | 3   | 2     | 1     | 0 |
|---------|---|------|-------|-----|------|-----|-------|-------|---|
| ACMPxSC | R | ACME | ACBGS | ACF | ACIE | ACO | ACOPE | ACMOD |   |
|         | W |      |       |     |      |     |       |       |   |

### 9.3.1 ACMPx Status and Control Register (ACMPxSC)

ACMPxSC contains the status flag and control bits used to enable and configure the ACMP.



**Figure 9-3. ACMPx Status and Control Register (ACMPxSC)**

**Table 9-3. ACMPxSC Field Descriptions**

| Field      | Description  |
|------------|--|
| 7<br>ACME  | Analog Comparator Module Enable. Enables the ACMP module.<br>0 ACMP not enabled<br>1 ACMP is enabled   |
| 6<br>ACBGS | Analog Comparator Bandgap Select. Selects between the bandgap reference voltage or the ACMPx+ pin as the input to the non-inverting input of the analog comparator.<br>0 External pin ACMPx+ selected as non-inverting input to comparator<br>1 Internal reference select as non-inverting input to comparator |
| 5<br>ACF   | Analog Comparator Flag. ACF is set when a compare event occurs. Compare events are defined by ACMOD. ACF is cleared by writing a one to it.<br>0 Compare event has not occurred<br>1 Compare event has occurred  |
| 4<br>ACIE  | Analog Comparator Interrupt Enable. Enables the interrupt from the ACMP. When ACIE is set, an interrupt is asserted when ACF is set.<br>0 Interrupt disabled<br>1 Interrupt enabled  |

## 10.1.5 Temperature Sensor

To use the on-chip temperature sensor, the user must perform the following:

- Configure ADC for long sample with a maximum of 1 MHz clock
- Convert the bandgap voltage reference channel (AD27)
  - By converting the digital value of the bandgap voltage reference channel using the value of  $V_{BG}$  the user can determine  $V_{DD}$ . For value of bandgap voltage, see [Section A.6, “DC Characteristics”](#).
- Convert the temperature sensor channel (AD26)
  - By using the calculated value of  $V_{DD}$ , convert the digital value of AD26 into a voltage,  $V_{TEMP}$

[Equation 10-1](#) provides an approximate transfer function of the temperature sensor.

$$\text{Temp} = 25 - ((V_{TEMP} - V_{TEMP25}) \div m) \quad \text{Eqn. 10-1}$$

where:

- $V_{TEMP}$  is the voltage of the temperature sensor channel at the ambient temperature.
- $V_{TEMP25}$  is the voltage of the temperature sensor channel at 25°C.
- $m$  is the hot or cold voltage versus temperature slope in V/°C.

For temperature calculations, use the  $V_{TEMP25}$  and  $m$  values from the ADC Electricals table.

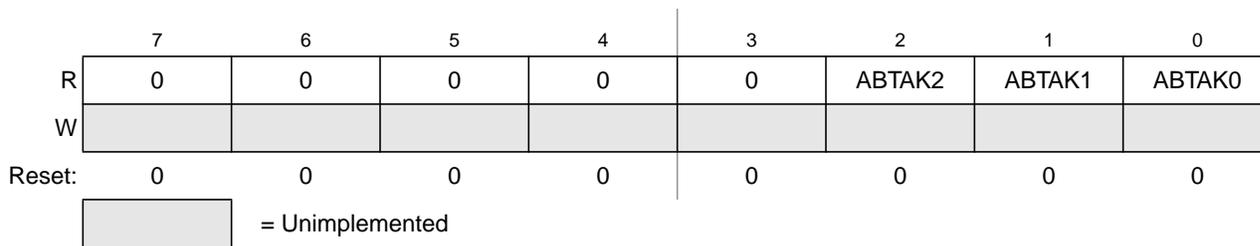
In application code, the user reads the temperature sensor channel, calculates  $V_{TEMP}$ , and compares to  $V_{TEMP25}$ . If  $V_{TEMP}$  is greater than  $V_{TEMP25}$  the cold slope value is applied in [Equation 10-1](#). If  $V_{TEMP}$  is less than  $V_{TEMP25}$  the hot slope value is applied in [Equation 10-1](#). To improve accuracy the user should calibrate the bandgap voltage reference and temperature sensor.

Calibrating at 25°C will improve accuracy to  $\pm 4.5^\circ\text{C}$ .

Calibration at three points, -40°C, 25°C, and 125°C will improve accuracy to  $\pm 2.5^\circ\text{C}$ . Once calibration has been completed, the user will need to calculate the slope for both hot and cold. In application code, the user would then calculate the temperature using [Equation 10-1](#) as detailed above and then determine if the temperature is above or below 25°C. Once determined if the temperature is above or below 25°C, the user can recalculate the temperature using the hot or cold slope value obtained during calibration.

### 12.3.9 MSCAN Transmitter Message Abort Acknowledge Register (CANTAAK)

The CANTAAK register indicates the successful abort of messages queued for transmission, if requested by the appropriate bits in the CANTARQ register.



**Figure 12-13. MSCAN Transmitter Message Abort Acknowledge Register (CANTAAK)**

#### NOTE

The CANTAAK register is held in the reset state when the initialization mode is active (INTRQ = 1 and INITAK = 1).

Read: Anytime

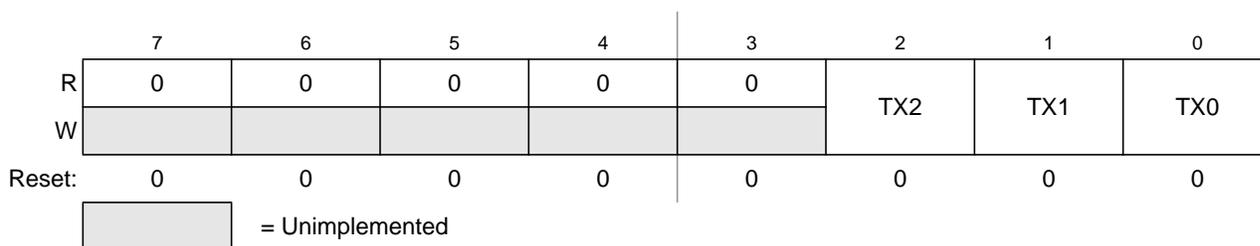
Write: Unimplemented for ABTAKx flags

**Table 12-14. CANTAAK Register Field Descriptions**

| Field             | Description  |
|-------------------|--|
| 2:0<br>ABTAK[2:0] | <p><b>Abort Acknowledge</b> — This flag acknowledges that a message was aborted due to a pending transmission abort request from the CPU. After a particular message buffer is flagged empty, this flag can be used by the application software to identify whether the message was aborted successfully or was sent anyway. The ABTAKx flag is cleared whenever the corresponding TXE flag is cleared.</p> <p>0 The message was not aborted.<br/>1 The message was aborted.</p> |

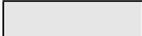
### 12.3.10 MSCAN Transmit Buffer Selection Register (CANTBSEL)

The CANTBSEL selections of the actual transmit message buffer, which is accessible in the CANTXFG register space.



**Figure 12-14. MSCAN Transmit Buffer Selection Register (CANTBSEL)**

| Register Name |   | Bit 7 | 6    | 5    | 4                  | 3                  | 2    | 1    | Bit0             |
|---------------|---|-------|------|------|--------------------|--------------------|------|------|------------------|
| IDR0          | R | ID28  | ID27 | ID26 | ID25               | ID24               | ID23 | ID22 | ID21             |
|               | W |       |      |      |                    |                    |      |      |                  |
| IDR1          | R | ID20  | ID19 | ID18 | SRR <sup>(1)</sup> | IDE <sup>(1)</sup> | ID17 | ID16 | ID15             |
|               | W |       |      |      |                    |                    |      |      |                  |
| IDR2          | R | ID14  | ID13 | ID12 | ID11               | ID10               | ID9  | ID8  | ID7              |
|               | W |       |      |      |                    |                    |      |      |                  |
| IDR3          | R | ID6   | ID5  | ID4  | ID3                | ID2                | ID1  | ID0  | RTR <sup>2</sup> |
|               | W |       |      |      |                    |                    |      |      |                  |
| DSR0          | R | DB7   | DB6  | DB5  | DB4                | DB3                | DB2  | DB1  | DB0              |
|               | W |       |      |      |                    |                    |      |      |                  |
| DSR1          | R | DB7   | DB6  | DB5  | DB4                | DB3                | DB2  | DB1  | DB0              |
|               | W |       |      |      |                    |                    |      |      |                  |
| DSR2          | R | DB7   | DB6  | DB5  | DB4                | DB3                | DB2  | DB1  | DB0              |
|               | W |       |      |      |                    |                    |      |      |                  |
| DSR3          | R | DB7   | DB6  | DB5  | DB4                | DB3                | DB2  | DB1  | DB0              |
|               | W |       |      |      |                    |                    |      |      |                  |
| DSR4          | R | DB7   | DB6  | DB5  | DB4                | DB3                | DB2  | DB1  | DB0              |
|               | W |       |      |      |                    |                    |      |      |                  |
| DSR5          | R | DB7   | DB6  | DB5  | DB4                | DB3                | DB2  | DB1  | DB0              |
|               | W |       |      |      |                    |                    |      |      |                  |
| DSR6          | R | DB7   | DB6  | DB5  | DB4                | DB3                | DB2  | DB1  | DB0              |
|               | W |       |      |      |                    |                    |      |      |                  |
| DSR7          | R | DB7   | DB6  | DB5  | DB4                | DB3                | DB2  | DB1  | DB0              |
|               | W |       |      |      |                    |                    |      |      |                  |
| DLR           | R |       |      |      |                    | DLC3               | DLC2 | DLC1 | DLC0             |
|               | W |       |      |      |                    |                    |      |      |                  |

 = Unused, always read 'x'

**Figure 12-23. Receive/Transmit Message Buffer — Extended Identifier Mapping**

<sup>1</sup> SRR and IDE are both 1s.

<sup>2</sup> The position of RTR differs between extended and standard identifier mapping.

**Read:** For transmit buffers, anytime when TXEx flag is set (see [Section 12.3.6, “MSCAN Transmitter Flag Register \(CANTFLG\)”](#)) and the corresponding transmit buffer is selected in CANTBSEL (see

### 12.5.7.1 Description of Interrupt Operation

The MSCAN supports four interrupt vectors (see Table 12-37), any of which can be individually masked (for details see sections from Section 12.3.5, “MSCAN Receiver Interrupt Enable Register (CANRIER),” to Section 12.3.7, “MSCAN Transmitter Interrupt Enable Register (CANTIER)”).

#### NOTE

The dedicated interrupt vector addresses are defined in the [Resets and Interrupts](#) chapter.

**Table 12-37. Interrupt Vectors**

| Interrupt Source                          | CCR Mask | Local Enable           |
|---|----------|------------------------|
| Wake-Up Interrupt (WUPIF)                 | 1 bit    | CANRIER (WUPIE)        |
| Error Interrupts Interrupt (CSCIF, OVRIF) | 1 bit    | CANRIER (CSCIE, OVRIE) |
| Receive Interrupt (RXF)                   | 1 bit    | CANRIER (RXFIE)        |
| Transmit Interrupts (TXE[2:0])            | 1 bit    | CANTIER (TXEIE[2:0])   |

### 12.5.7.2 Transmit Interrupt

At least one of the three transmit buffers is empty (not scheduled) and can be loaded to schedule a message for transmission. The TXEx flag of the empty message buffer is set.

### 12.5.7.3 Receive Interrupt

A message is successfully received and shifted into the foreground buffer (RxFG) of the receiver FIFO. This interrupt is generated immediately after receiving the EOF symbol. The RXF flag is set. If there are multiple messages in the receiver FIFO, the RXF flag is set as soon as the next message is shifted to the foreground buffer.

### 12.5.7.4 Wake-Up Interrupt

A wake-up interrupt is generated if activity on the CAN bus occurs during MSCAN internal sleep mode. WUPE (see Section 12.3.1, “MSCAN Control Register 0 (CANCTL0)”) must be enabled.

### 12.5.7.5 Error Interrupt

An error interrupt is generated if an overrun of the receiver FIFO, error, warning, or bus-off condition occurs. Section 12.3.4.1, “MSCAN Receiver Flag Register (CANRFLG) indicates one of the following conditions:

- **Overrun** — An overrun condition of the receiver FIFO as described in Section 12.5.2.3, “Receive Structures,” occurred.
- **CAN Status Change** — The actual value of the transmit and receive error counters control the CAN bus state of the MSCAN. As soon as the error counters skip into a critical range (Tx/Rx-warning, Tx/Rx-error, bus-off) the MSCAN flags an error condition. The status change, which caused the error condition, is indicated by the TSTAT and RSTAT flags (see

**Table 14-6. SC1xS1 Field Descriptions**

| Field     | Description   |
|-----------|---|
| 7<br>TDRE | <p><b>Transmit Data Register Empty Flag</b> — TDRE is set out of reset and when a transmit data value transfers from the transmit data buffer to the transmit shifter, leaving room for a new character in the buffer. To clear TDRE, read SC1xS1 with TDRE = 1 and then write to the SCI data register (SC1xD).</p> <p>0 Transmit data register (buffer) full.<br/>1 Transmit data register (buffer) empty.</p>  |
| 6<br>TC   | <p><b>Transmission Complete Flag</b> — TC is set out of reset and when TDRE = 1 and no data, preamble, or break character is being transmitted.</p> <p>0 Transmitter active (sending data, a preamble, or a break).<br/>1 Transmitter idle (transmission activity complete).</p> <p>TC is cleared automatically by reading SC1xS1 with TC = 1 and then doing one of the following three things:</p> <ul style="list-style-type: none"> <li>• Write to the SCI data register (SC1xD) to transmit new data</li> <li>• Queue a preamble by changing TE from 0 to 1</li> <li>• Queue a break character by writing 1 to SBK in SC1xC2</li> </ul>   |
| 5<br>RDRF | <p><b>Receive Data Register Full Flag</b> — RDRF becomes set when a character transfers from the receive shifter into the receive data register (SC1xD). To clear RDRF, read SC1xS1 with RDRF = 1 and then read the SCI data register (SC1xD).</p> <p>0 Receive data register empty.<br/>1 Receive data register full.</p>  |
| 4<br>IDLE | <p><b>Idle Line Flag</b> — IDLE is set when the SCI receive line becomes idle for a full character time after a period of activity. When ILT = 0, the receiver starts counting idle bit times after the start bit. So if the receive character is all 1s, these bit times and the stop bit time count toward the full character time of logic high (10 or 11 bit times depending on the M control bit) needed for the receiver to detect an idle line. When ILT = 1, the receiver doesn't start counting idle bit times until after the stop bit. So the stop bit and any logic high bit times at the end of the previous character do not count toward the full character time of logic high needed for the receiver to detect an idle line.</p> <p>To clear IDLE, read SC1xS1 with IDLE = 1 and then read the SCI data register (SC1xD). After IDLE has been cleared, it cannot become set again until after a new character has been received and RDRF has been set. IDLE will get set only once even if the receive line remains idle for an extended period.</p> <p>0 No idle line detected.<br/>1 Idle line was detected.</p> |
| 3<br>OR   | <p><b>Receiver Overrun Flag</b> — OR is set when a new serial character is ready to be transferred to the receive data register (buffer), but the previously received character has not been read from SC1xD yet. In this case, the new character (and all associated error information) is lost because there is no room to move it into SC1xD. To clear OR, read SC1xS1 with OR = 1 and then read the SCI data register (SC1xD).</p> <p>0 No overrun.<br/>1 Receive overrun (new SCI data lost).</p>  |
| 2<br>NF   | <p><b>Noise Flag</b> — The advanced sampling technique used in the receiver takes seven samples during the start bit and three samples in each data bit and the stop bit. If any of these samples disagrees with the rest of the samples within any bit time in the frame, the flag NF will be set at the same time as the flag RDRF gets set for the character. To clear NF, read SC1xS1 and then read the SCI data register (SC1xD).</p> <p>0 No noise detected.<br/>1 Noise detected in the received character in SC1xD.</p>   |

- Non-intrusive commands can be executed at any time even while the user's program is running. Non-intrusive commands allow a user to read or write MCU memory locations or access status and control registers within the background debug controller.

Typically, a relatively simple interface pod is used to translate commands from a host computer into commands for the custom serial interface to the single-wire background debug system. Depending on the development tool vendor, this interface pod may use a standard RS-232 serial port, a parallel printer port, or some other type of communications such as a universal serial bus (USB) to communicate between the host PC and the pod. The pod typically connects to the target system with ground, the BKGD pin,  $\overline{\text{RESET}}$ , and sometimes  $V_{\text{DD}}$ . An open-drain connection to reset allows the host to force a target system reset, which is useful to regain control of a lost target system or to control startup of a target system before the on-chip nonvolatile memory has been programmed. Sometimes  $V_{\text{DD}}$  can be used to allow the pod to use power from the target system to avoid the need for a separate power supply. However, if the pod is powered separately, it can be connected to a running target system without forcing a target system reset or otherwise disturbing the running application program.

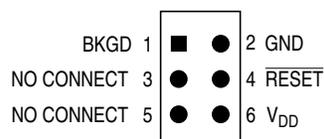


Figure 17-1. BDM Tool Connector

## 17.2.1 BKGD Pin Description

BKGD is the single-wire background debug interface pin. The primary function of this pin is for bidirectional serial communication of active background mode commands and data. During reset, this pin is used to select between starting in active background mode or starting the user's application program. This pin is also used to request a timed sync response pulse to allow a host development tool to determine the correct clock frequency for background debug serial communications.

BDC serial communications use a custom serial protocol first introduced on the M68HC12 Family of microcontrollers. This protocol assumes the host knows the communication clock rate that is determined by the target BDC clock rate. All communication is initiated and controlled by the host that drives a high-to-low edge to signal the beginning of each bit time. Commands and data are sent most significant bit first (MSB first). For a detailed description of the communications protocol, refer to [Section 17.2.2, "Communication Details."](#)

If a host is attempting to communicate with a target MCU that has an unknown BDC clock rate, a SYNC command may be sent to the target MCU to request a timed sync response signal from which the host can determine the correct communication speed.

BKGD is a pseudo-open-drain pin and there is an on-chip pullup so no external pullup resistor is required. Unlike typical open-drain pins, the external RC time constant on this pin, which is influenced by external capacitance, plays almost no role in signal rise time. The custom protocol provides for brief, actively driven speedup pulses to force rapid rise times on this pin without risking harmful drive level conflicts. Refer to [Section 17.2.2, "Communication Details,"](#) for more detail.

Figure 17-2 shows an external host transmitting a logic 1 or 0 to the BKGD pin of a target HCS08 MCU. The host is asynchronous to the target so there is a 0-to-1 cycle delay from the host-generated falling edge to where the target perceives the beginning of the bit time. Ten target BDC clock cycles later, the target senses the bit level on the BKGD pin. Typically, the host actively drives the pseudo-open-drain BKGD pin during host-to-target transmissions to speed up rising edges. Because the target does not drive the BKGD pin during the host-to-target transmission period, there is no need to treat the line as an open-drain signal during this period.

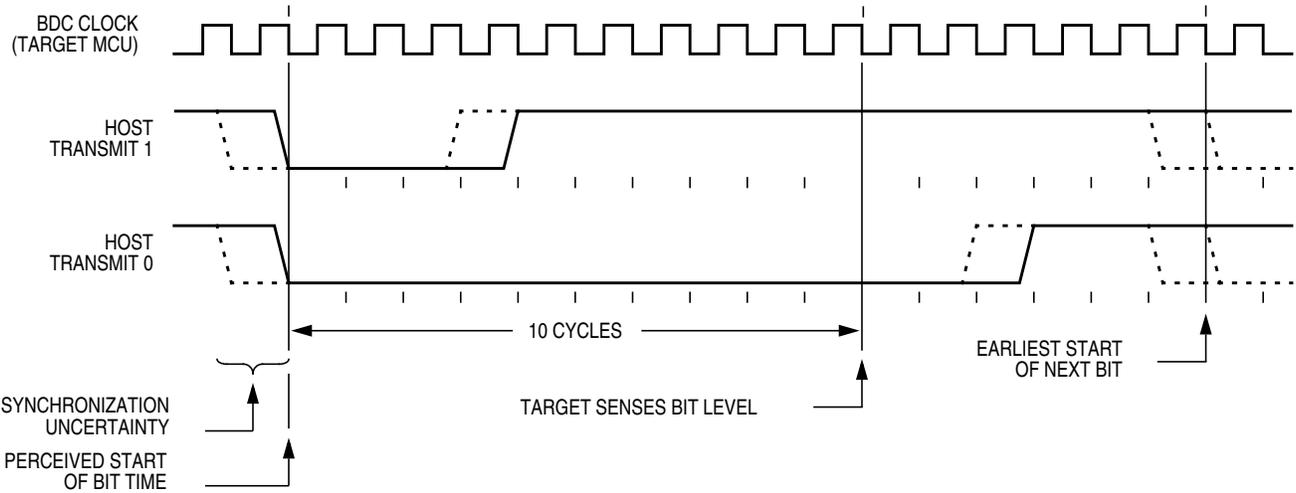


Figure 17-2. BDC Host-to-Target Serial Bit Timing

The SYNC command is unlike other BDC commands because the host does not necessarily know the correct communications speed to use for BDC communications until after it has analyzed the response to the SYNC command.

To issue a SYNC command, the host:

- Drives the BKGD pin low for at least 128 cycles of the slowest possible BDC clock (The slowest clock is normally the reference oscillator/64 or the self-clocked rate/64.)
- Drives BKGD high for a brief speedup pulse to get a fast rise time (This speedup pulse is typically one cycle of the fastest clock in the system.)
- Removes all drive to the BKGD pin so it reverts to high impedance
- Monitors the BKGD pin for the sync response pulse

The target, upon detecting the SYNC request from the host (which is a much longer low time than would ever occur during normal BDC communications):

- Waits for BKGD to return to a logic high
- Delays 16 cycles to allow the host to stop driving the high speedup pulse
- Drives BKGD low for 128 BDC clock cycles
- Drives a 1-cycle high speedup pulse to force a fast rise time on BKGD
- Removes all drive to the BKGD pin so it reverts to high impedance

The host measures the low time of this 128-cycle sync response pulse and determines the correct speed for subsequent BDC communications. Typically, the host can determine the correct communication speed within a few percent of the actual target speed and the communication protocol can easily tolerate speed errors of several percent.

## 17.2.4 BDC Hardware Breakpoint

The BDC includes one relatively simple hardware breakpoint that compares the CPU address bus to a 16-bit match value in the BDCBKPT register. This breakpoint can generate a forced breakpoint or a tagged breakpoint. A forced breakpoint causes the CPU to enter active background mode at the first instruction boundary following any access to the breakpoint address. The tagged breakpoint causes the instruction opcode at the breakpoint address to be tagged so that the CPU will enter active background mode rather than executing that instruction if and when it reaches the end of the instruction queue. This implies that tagged breakpoints can only be placed at the address of an instruction opcode while forced breakpoints can be set at any address.

The breakpoint enable (BKPTEN) control bit in the BDC status and control register (BDCSCR) is used to enable the breakpoint logic (BKPTEN = 1). When BKPTEN = 0, its default value after reset, the breakpoint logic is disabled and no BDC breakpoints are requested regardless of the values in other BDC breakpoint registers and control bits. The force/tag select (FTS) control bit in BDCSCR is used to select forced (FTS = 1) or tagged (FTS = 0) type breakpoints.

The on-chip debug module (DBG) includes circuitry for two additional hardware breakpoints that are more flexible than the simple breakpoint in the BDC module.

<sup>3</sup> Monotonicity and No-Missing-Codes guaranteed in 10 bit and 8 bit modes

<sup>4</sup> Based on input pad leakage current. Refer to pad electricals.

## A.10 External Oscillator (XOSC) Characteristics

**Table A-11. Oscillator Electrical Specifications (Temperature Range = -40 to 125°C Ambient)**

| Num   | C              | Rating   | Symbol         | Min   | Typ <sup>1</sup> | Max  | Unit |  |
|---|----------------|--|----------------|---|------------------|------|------|--|
| 1   | C              | Oscillator crystal or resonator (EREFS = 1, ERCLKEN = 1)   |                |   |                  |      |      |  |
|   |                | Low range (RANGE = 0)                                      | $f_{lo}$       | 32  | —                | 38.4 | kHz  |  |
|   |                | High range (RANGE = 1) FEE or FBE mode <sup>2</sup>        | $f_{hi-fl}$    | 1   | —                | 5    | MHz  |  |
|   |                | High range (RANGE = 1) PEE or PBE mode <sup>3</sup>        | $f_{hi-pll}$   | 1   | —                | 16   | MHz  |  |
|   |                | High range (RANGE = 1, HGO = 1) BLPE mode                  | $f_{hi-hgo}$   | 1   | —                | 16   | MHz  |  |
|   |                | High range (RANGE = 1, HGO = 0) BLPE mode                  | $f_{hi-lp}$    | 1   | —                | 8    | MHz  |  |
| 2   | —              | Load capacitors  | $C_1$<br>$C_2$ | See crystal or resonator manufacturer's recommendation. |                  |      |      |  |
| 3   | —              | Feedback resistor  |                |   |                  |      |      |  |
|   |                | Low range (32 kHz to 100 kHz)                              | $R_F$          | —   | 10               | —    | MΩ   |  |
| High range (1 MHz to 16 MHz)                            | —              | 1  |                | —   | MΩ               |      |      |  |
| 4   | —              | Series resistor  |                |   |                  |      |      |  |
|   |                | Low range, low gain (RANGE = 0, HGO = 0)                   | $R_S$          | —   | 0                | —    | kΩ   |  |
|   |                | Low range, high gain (RANGE = 0, HGO = 1)                  |                | —   | 100              | —    |      |  |
|   |                | High range, low gain (RANGE = 1, HGO = 0)                  |                | —   | 0                | —    |      |  |
|   |                | High range, high gain (RANGE = 1, HGO = 1) ≥ 8 MHz         |                | —   | 0                | 0    |      |  |
| 4 MHz   | —              | 0  |                | 10  |                  |      |      |  |
| 1 MHz   | —              | 0  | 20             |   |                  |      |      |  |
| 5   | T              | Crystal start-up time <sup>4</sup>                         |                |   |                  |      |      |  |
|   |                | Low range, low gain (RANGE = 0, HGO = 0)                   | $t_{CSTL-LP}$  | —   | 200              | —    | ms   |  |
|   |                | Low range, high gain (RANGE = 0, HGO = 1)                  | $t_{CSTL-HGO}$ | —   | 400              | —    |      |  |
|   |                | High range, low gain (RANGE = 1, HGO = 0) <sup>5</sup>     | $t_{CSTH-LP}$  | —   | 5                | —    |      |  |
| High range, high gain (RANGE = 1, HGO = 1) <sup>4</sup> | $t_{CSTH-HGO}$ | —  | 15             | —   |                  |      |      |  |
| 6   | T              | Square wave input clock frequency (EREFS = 0, ERCLKEN = 1) |                |   |                  |      |      |  |
|   |                | FEE or FBE mode <sup>2</sup>                               | $f_{extal}$    | 0.03125   | —                | 5    | MHz  |  |
|   |                | PEE or PBE mode <sup>3</sup>                               |                | 1   | —                | 16   |      |  |
| BLPE mode   | 0              | —  |                | 40  |                  |      |      |  |

<sup>1</sup> Typical data was characterized at 3.0 V, 25°C or is recommended value.

<sup>2</sup> When MCG is configured for FEE or FBE mode, the input clock source must be divisible using RDIV to within the range of 31.25 kHz to 39.0625 kHz.

<sup>3</sup> When MCG is configured for PEE or PBE mode, input clock source must be divisible using RDIV to within the range of 1 MHz to 2 MHz.

<sup>4</sup> This parameter is characterized and not tested on each device. Proper PC board layout procedures must be followed to achieve specifications. This data will vary based upon the crystal manufacturer and board design. The crystal should be characterized by the crystal manufacturer.

<sup>5</sup> 4 MHz crystal.

All TPM channels are programmable independently as input capture, output compare, or buffered edge-aligned PWM channels.

## B.1 External Signal Description

When any pin associated with the timer is configured as a timer input, a passive pullup can be enabled. After reset, the TPM modules are disabled and all pins default to general-purpose inputs with the passive pullups disabled.

### B.1.1 External TPM Clock Sources

When control bits CLKSB:CLKSA in the timer status and control register are set to 1:1, the prescaler and consequently the 16-bit counter for TPMx are driven by an external clock source, TPMxCLK, connected to an I/O pin. A synchronizer is needed between the external clock and the rest of the TPM. This synchronizer is clocked by the bus clock so the frequency of the external source must be less than one-half the frequency of the bus rate clock. The upper frequency limit for this external clock source is specified to be one-fourth the bus frequency to conservatively accommodate duty cycle and phase-locked loop (PLL) or frequency-locked loop (FLL) frequency jitter effects.

On some devices the external clock input is shared with one of the TPM channels. When a TPM channel is shared as the external clock input, the associated TPM channel cannot use the pin. (The channel can still be used in output compare mode as a software timer.) Also, if one of the TPM channels is used as the external clock input, the corresponding ELSnB:ELSnA control bits must be set to 0:0 so the channel is not trying to use the same pin.

### B.1.2 TPMxCHn — TPMx Channel n I/O Pins

Each TPM channel is associated with an I/O pin on the MCU. The function of this pin depends on the configuration of the channel. In some cases, no pin function is needed so the pin reverts to being controlled by general-purpose I/O controls. When a timer has control of a port pin, the port data and data direction registers do not affect the related pin(s). See the [Pins and Connections](#) chapter for additional information about shared pin functions.

## B.2 Register Definition

The TPM includes:

- An 8-bit status and control register (TPMxSC)
- A 16-bit counter (TPMxCNTH:TPMxCNTL)
- A 16-bit modulo register (TPMxMODH:TPMxMODL)

Each timer channel has:

- An 8-bit status and control register (TPMxCnSC)
- A 16-bit channel value register (TPMxCnVH:TPMxCnVL)

Refer to the direct-page register summary in the [Memory](#) chapter of this data sheet for the absolute address assignments for all TPM registers. This section refers to registers and control bits only by their names. A